

# SPECIFICATION

*PART NO. : LT631Y-H103*

**2.9mm ROUND LED LAMP WITH HOLDER**



Approved by

Checked by

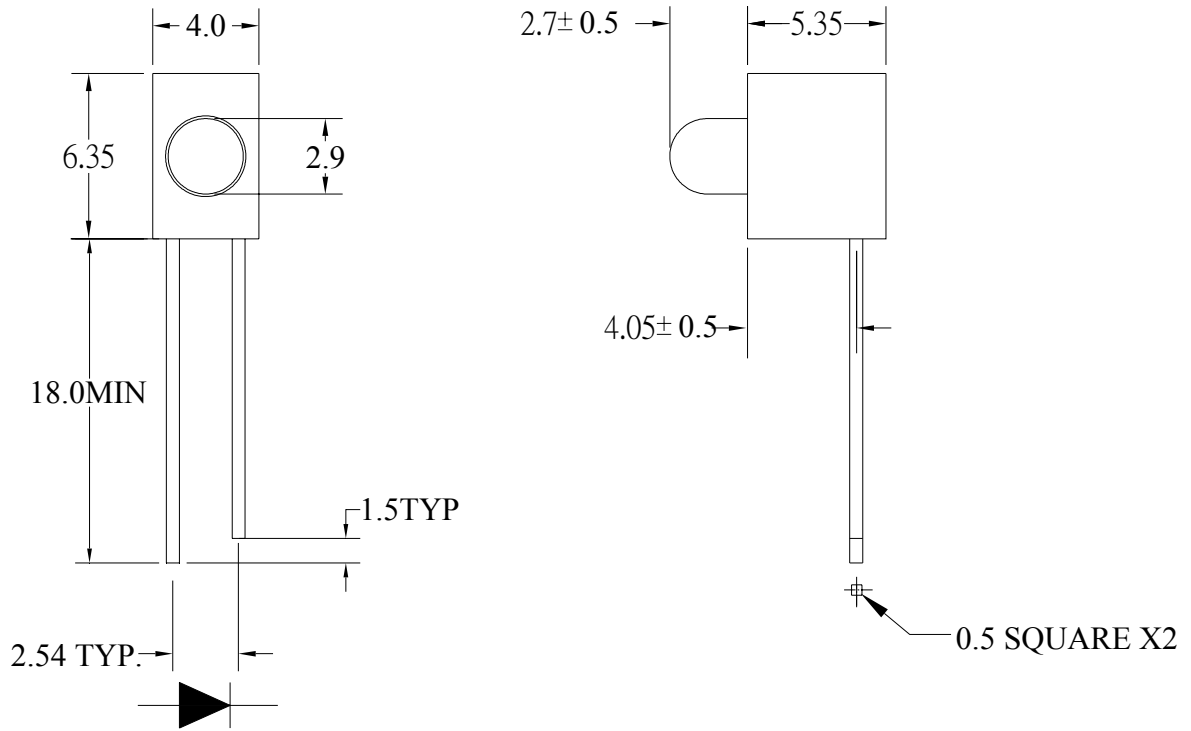
Prepared by

*SAN*

*Sunny*

*Angel*

**Package Dimensions**



Notes:

1. All dimensions are in millimeters.
2. Tolerance is ±0.25mm unless otherwise noted.
3. The color of holder:Black.

**Description**

Part No.	LED Chip		Description
	Material	Emitting Color	
LT631Y-H103	GaAsP/GaP	Yellow	Yellow Diffused

**LT631Y-H103**2.9mm ROUND LED  
LAMP WITH HOLDER**Absolute Maximum Ratings at Ta=25 °C**

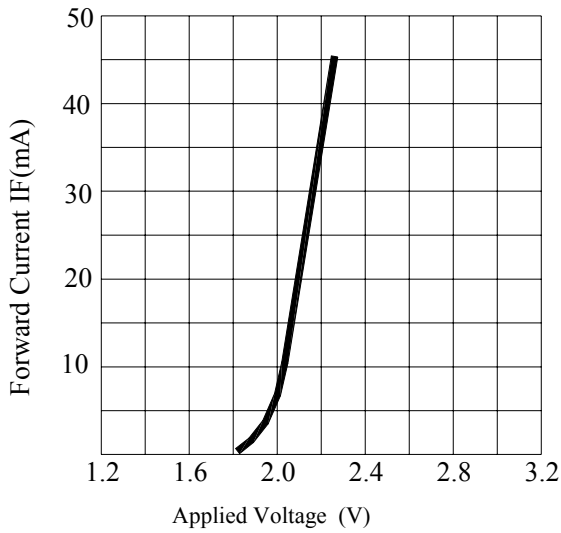
Parameter	Symbol	Rating	Unit
Power Dissipation	P <sub>D</sub>	78	mW
Reverse Voltage	V <sub>R</sub>	5	V
D.C. Forward Current	I <sub>f</sub>	30	mA
Peak Current(1/10Duty duty,0.1ms Pulse Width.)	I <sub>f</sub> (Peak)	100	mA
Operating Temperature Range	T <sub>opr.</sub>	-25 to +85	°C
Storage Temperature Range	T <sub>stg.</sub>	-40 to +100	°C
Lead Soldering Temp.(1.6mm from body) for 5 seconds		260	°C

**Electrical and Optical Characteristics:**

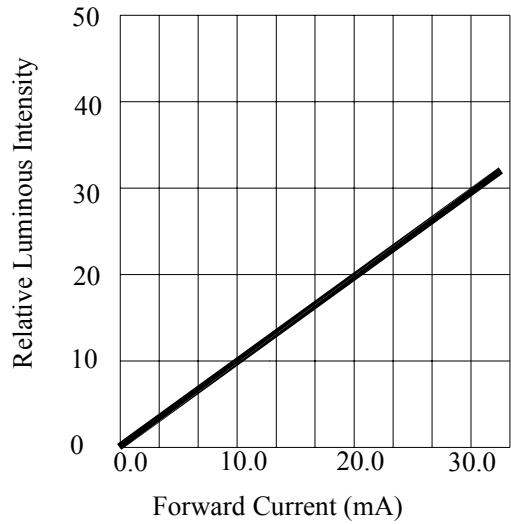
Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Luminous Intensity	I <sub>v</sub>	I <sub>f</sub> =20mA	12.0	20.0		mcd
Forward Voltage	V <sub>f</sub>	I <sub>f</sub> =20mA		2.1	2.6	V
Peak Wavelength	λ <sub>P</sub>	I <sub>f</sub> =20mA		585		nm
Dominant Wavelength	λ <sub>D</sub>	I <sub>f</sub> =20mA		590		nm
Reverse Current	I <sub>r</sub>	V <sub>r</sub> =5V			100	μA
Viewing Angle	2 θ 1/2	I <sub>f</sub> =20mA		55		deg
Spectrum Line Halfwidth	Δλ	I <sub>f</sub> =20mA		35		nm

NOTE: THE DATAS COME FROM THE SPEC. OF LT6331-41

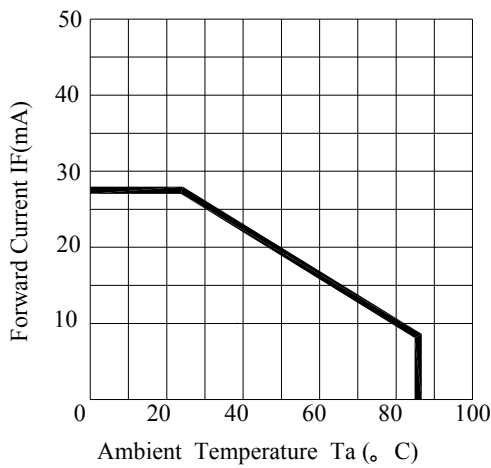
**Typical Electrical/Optical Characteristic Curves  
(25°C Ambient Temperature Unless Otherwise Noted)**



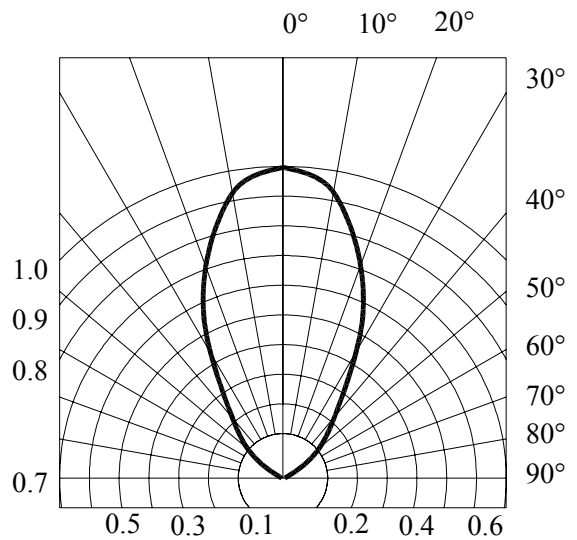
**FORWARD CURRENT VS. APPLIED VOLTAGE**



**FORWARD CURRENT VS. LUMINOUS INTENSITY**



**AMBIENT TEMPERATURE VS. FORWARD CURRENT**



**RADIATION DIAGRAM**

**Precautions in Use:**

**Storage**

Recommend storage environment

Temperature : 5 ~30

**Soldering**

**Reflow Soldering**

Recommend use of upper and lower heater type reflow furnace.

300°C Max for up to 5 seconds.

Pre-heat is 150°C Max for up to 2 minutes Max.

In case of screen-printing, keep metal mask thickness between 0.2mm and 0.3mm.

**Manual Iron Soldering (NOT RECOMMENDED)**

Use SN60 solder of solder with silver content.

Use 25W soldering iron at 300°C Max for 5 seconds or less.

Must not touch top resin portion of lamp by heated soldering iron.

**Cleaning**

Surface condition of this device may change when organic solvents such as trichloroethylene or acetone were applied.

Avoid using organic solvent.

Recommend ultrasonic method 300W Max.

**Reflow Temp/Time:**

